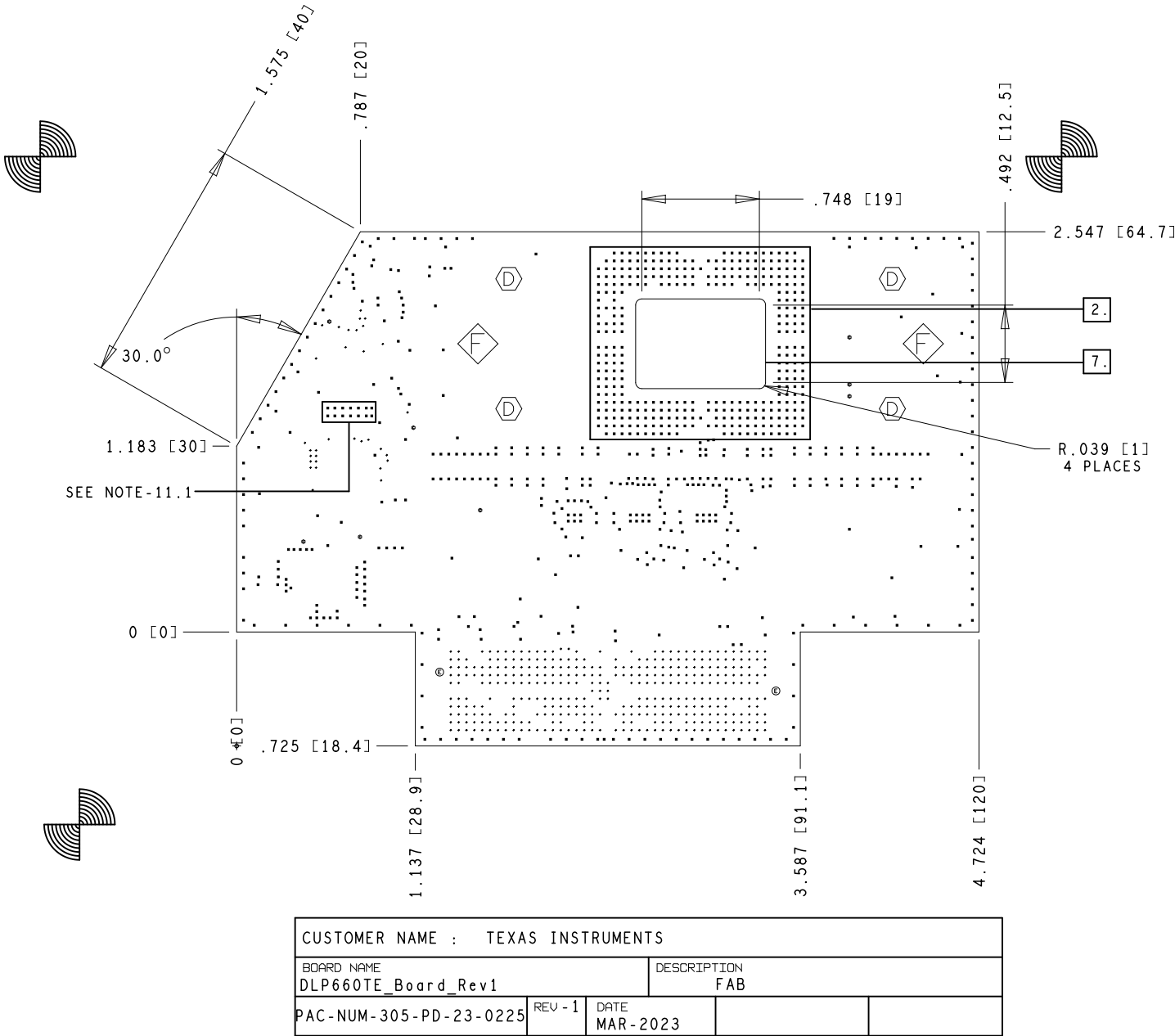


DRILL CHART: TOP +o BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	10.0	+3.0/-10.0	PLATED	385
.	12.0	+3.0/-12.0	PLATED	822
.	24.0	+3.0/-3.0	PLATED	8
D	166.0	+3.0/-3.0	PLATED	4
o	50.0	+2.0/-0.0	NON-PLATED	2
F	256.0	+3.0/-3.0	NON-PLATED	2



FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES[MM], UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010"
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL - REFER STACKUP  
RoHS COMPLIANT AND LEAD FREE  
ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- ALL BOARDS MUST MEET OR EXCEED UL94V - 0 REQUIREMENTS.  
PCB MUST BEAR THE UL94V - 0 UL REGISTERED MATERIAL ID NUMBER.
- NO VENDOR LOGO, ART WORKS SHOULD NOT BE CHANGED WITHOUT PRIOR APPROVAL FROM TEXAS INSTRUMENTS
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .092 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- ALL HOLES IN DRILL CHART ARE FINISHED HOLE SIZES (FHS).

PROCESS NOTES:

- EXCEPT AS NOTED IN NOTE 2, PLATE ALL EXPOSED AREAS WITH ELECTROLYTIC IMMERSION GOLD. NICKEL 100 MICROINCHES THK GOLD 2-6 MICROINCHES THK MIN.
2. PLATE INDICATED PAD AREAS WITH 150 MICROINCHES MIN. LOW STRESS NICKEL UNDER 5-15 MICROINCHES GOLD HAVING A HARDNESS OF KNOOP14.
- APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC).  
COLOR: BLUE. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
- SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS.  
FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.  
WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK.  
COLOR: WHITE.
- ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.  
PCB MUST BEAR THE UL94-V0 UL REGISTERED MATERIAL ID NUMBER.
7. CUT THE BOARD AS PER MARKED DIMENSION
- TEARDROPS SHOULD NOT BE ADDED ON ANY AREA WITHOUT PRIOR APPROVAL FROM TEXAS INSTRUMENTS
- DEBURR ALL SHARP EDGES
- REMOVE UNUSED PADS IN ALL INNER LAYERS
- ALL 10,12 MIL VIAS(EXCEPT MARKED REGION) NEED TO BE SOLDERMASK PLUGGING ON TOP SIDE  
11.1 MARKED REGION VIAS NEED TO BE SOLDERMASK PLUGGING ON BOTTOM SIDE
- CLIP SILKSCREEN ON NO MASK AREA

STACKUP: 14 LAYERS		IMPEDANCE TABLE: 50 OHM +/- 10%	IMPEDANCE TABLE: 100 OHM +/- 10%
TOP (1 oz + PLATING)		7.9 MIL	-----
FR4_HTG	DIELECTRIC (4.65 mils)		
	02_GND1 (1 oz)		
FR4_HTG	DIELECTRIC (7.87 mils)		
	03_SIG1 (0.5 oz)	4.7 MIL	4.18/7.82 MIL
FR4_HTG	DIELECTRIC (4.23 mils)		
	04_GND2 (1 oz)		
FR4_HTG	DIELECTRIC (7.87 mils)		
	05_SIG2 (0.5 oz)	-----	4.18/7.82 MIL
FR4_HTG	DIELECTRIC (4.23 mils)		
	06_GND3 (1 oz)		
FR4_HTG	DIELECTRIC (3.937 mils)		
	07_SIG3 (0.5 oz)	4.34 MIL	3.87/8.13 MIL
FR4_HTG	DIELECTRIC (8.425 mils)		
	08_SIG4 (0.5 oz)	4.34 MIL	-----
FR4_HTG	DIELECTRIC (3.937 mils)		
	09_PWR (1 oz)		
FR4_HTG	DIELECTRIC (4.23 mils)		
	10_SIG5 (0.5 oz)	-----	4.18/7.82 MIL
FR4_HTG	DIELECTRIC (7.87 mils)		
	11_GND4 (1 oz)		
FR4_HTG	DIELECTRIC (4.23 mils)		
	12_SIG6 (0.5 oz)	-----	4.18/7.82 MIL
FR4_HTG	DIELECTRIC (7.87 mils)		
	13_GND5 (1 oz)		
FR4_HTG	DIELECTRIC (4.65 mils)		
BOTTOM (1 oz + PLATING)		7.9 MIL	5.58/6.92 MIL
TOTAL THICKNESS: 92 mils +/-10%			